



FDP51N25 / FDPF51N25 250V N-Channel MOSFET

Features

- 51A, 250V, $R_{DS(on)} = 0.06\Omega$ @ $V_{GS} = 10 V$
- Low gate charge (typical 55 nC)
- Low Crss (typical 63 pF)
- · Fast switching
- · Improved dv/dt capability



Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficient switched mode power supplies and active power factor correction.



Absolute Maximum Ratings

Symbol		Parameter		FDP51N25	FDPF51N25	Unit
V _{DSS}	Drain-Source Voltage		250		V	
I _D	Drain Current	- Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		51 30	51* 30*	A A
I _{DM}	Drain Current	- Pulsed	(Note 1)	204	204*	А
V _{GSS}	Gate-Source voltage		± 30		V	
E _{AS}	Single Pulsed Avalanche Energy		(Note 2)	1111		mJ
I _{AR}	Avalanche Current		(Note 1)	51		А
E _{AR}	Repetitive Avalanche Energy		(Note 1)	32		mJ
dv/dt	Peak Diode Recovery dv/dt		(Note 3)	4.5		V/ns
P _D	Power Dissipation	(T _C = 25°C) - Derate above 25°C		320 3.7	38 0.3	W W/°C
T _{J,} T _{STG}	Operating and Storage Temperature Range		-55 to +150		°C	
T _L	Maximum Lead Temperature for Soldering Purpose, 1/8" from Case for 5 Seconds		300		°C	

^{*}Drain current limited by maximum junction temperature

Thermal Characteristics

Symbol	Parameter	FDP51N25	FDPF51N25	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	0.39	3.3	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink Typ.	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	62.5	62.5	°C/WJ

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDP51N25	FDP51N25	TO-220	-	-	50
FDPF51N25	FDPF51N25	TO-220F	-	-	50

Electrical Characteristics T_C = 25°C unless otherwise noted

Symbol	Parameter	Conditions	Min	Тур	Max	Units
Off Charac	teristics	-				
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V$, $I_D = 250\mu A$, $T_J = 25^{\circ}C$	250			V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250μA, Referenced to 25°C		0.25		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 250V, V_{GS} = 0V$ $V_{DS} = 200V, T_C = 125^{\circ}C$			1 10	μ Α μ Α
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30V, V _{DS} = 0V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30V, V _{DS} = 0V			-100	nA
On Charac	teristics					
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	3.0		5.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10V, I _D = 25.5A	3	0.048	0.060	Ω
9 _{FS}	Forward Transconductance	$V_{DS} = 40V, I_D = 25.5A$ (Note 4)		43		S
Dynamic C	haracteristics	132				
C _{iss}	Input Capacitance	$V_{DS} = 25V$, $V_{GS} = 0V$,		2620	3410	pF
C _{oss}	Output Capacitance	f = 1.0MHz		530	690	pF
C _{rss}	Reverse Transfer Capacitance			63	90	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time	P 250		62	135	ns
t _r	Turn-On Rise Time			465	940	ns
$t_{d(off)}$	Turn-Off Delay Time			98	205	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		130	270	ns
Qg	Total Gate Charge	V _{DS} = 200V, I _D = 51A		55	70	nC
Q _{gs}	Gate-Source Charge	V _{GS} = 10V		16		nC
Q_{gd}	Gate-Drain Charge (Note 4, 5			27		nC
Drain-Sour	ce Diode Characteristics and Maximun	n Ratings				
I _S Maximum Continuous Drain-Source Diode Forward Current					51	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current				204	Α
V_{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0V, I _S = 51A			1.4	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0V, I _S = 51A		178		ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100A/\mu s $ (Note 4)		4.0		μС

Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L = 0.68mH, I $_{AS}$ = 51A, V $_{DD}$ = 50V, R $_{G}$ = 25 Ω , Starting T $_{J}$ = 25°C
- 3. I $_{SD} \leq$ 51A, di/dt \leq 200A/µs, V $_{DD} \leq$ BV $_{DSS}$, Starting T $_{J}$ = 25°C
- 4. Pulse Test: Pulse width $\leq 300 \mu s, \ \text{Duty Cycle} \leq 2\%$
- 5. Essentially Independent of Operating Temperature Typical Characteristics

Typical Performance Characteristics

Figure 1. On-Region Characteristics

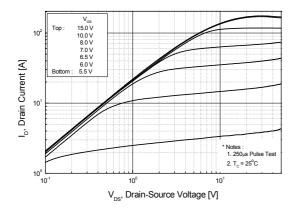


Figure 3. On-Resistance Variation vs.
Drain Current and Gate Voltage

Figure 2. Transfer Characteristics

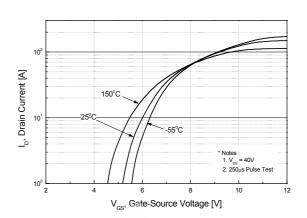


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperatue

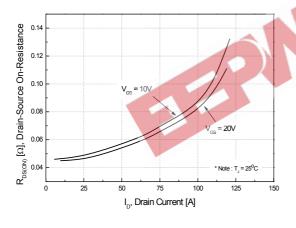
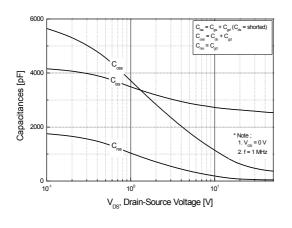
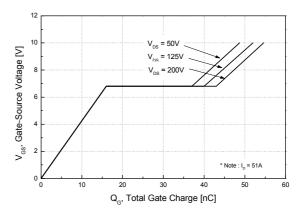


Figure 5. Capacitance Characteristics



Notes:
10°
10°
150°C
25°C
Notes:
1. V_{css} = 0V
2. 250µs Pulse Test
V_{SD}, Source-Drain voltage [V]

Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

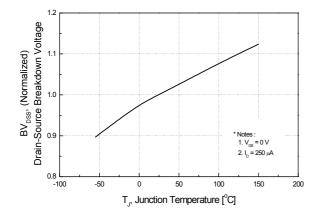


Figure 9-1. Maximum Safe Operating Area for FDP51N25

Figure 8. On-Resistance Variation vs. Temperature

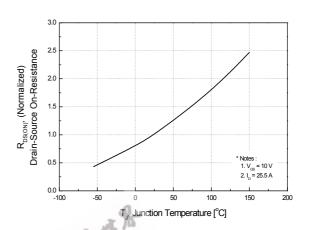


Figure 9-2. Maximum Safe Operating Area for FDPF51N25

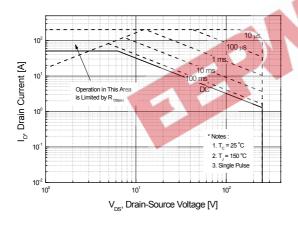
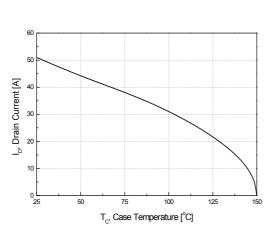
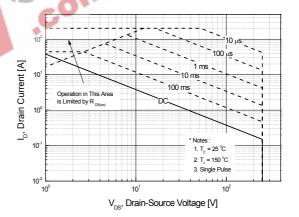


Figure 10. Maximum Drain Current vs. Case Temperature





Typical Performance Characteristics (Continued)

Figure 11-1. Transient Thermal Response Curve for FDP51N25

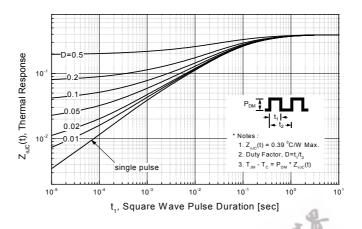
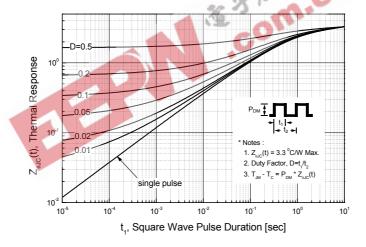
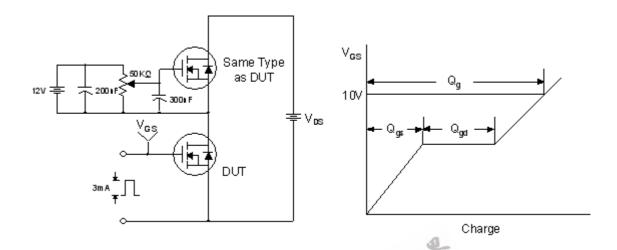


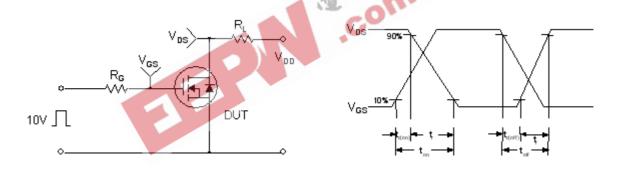
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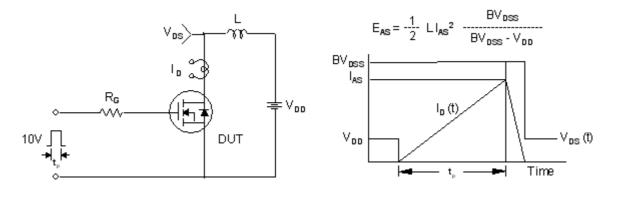
Gate Charge Test Circuit & Waveform



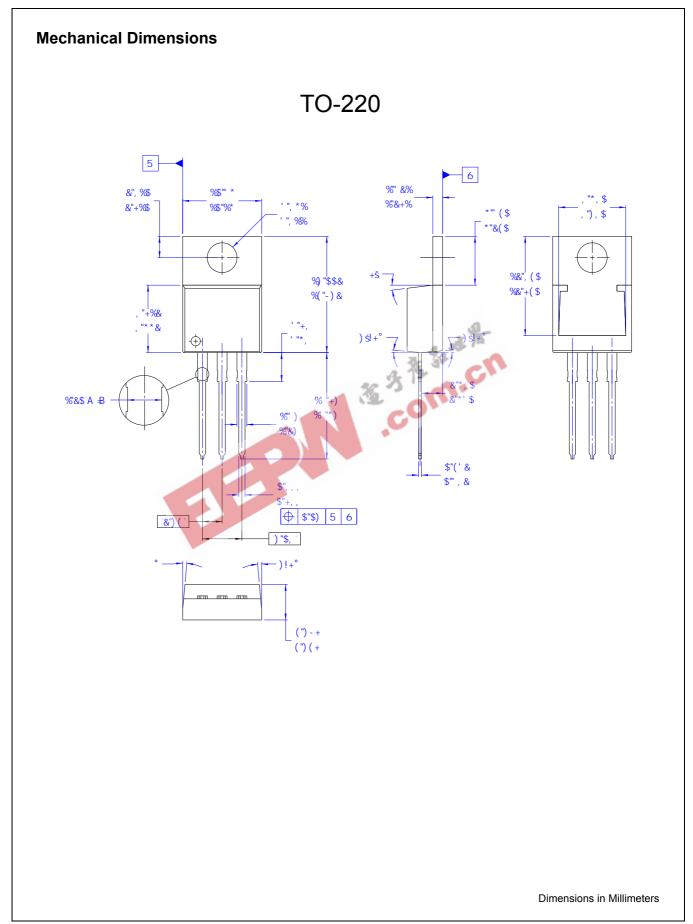
Resistive Switching Test Circuit & Waveforms

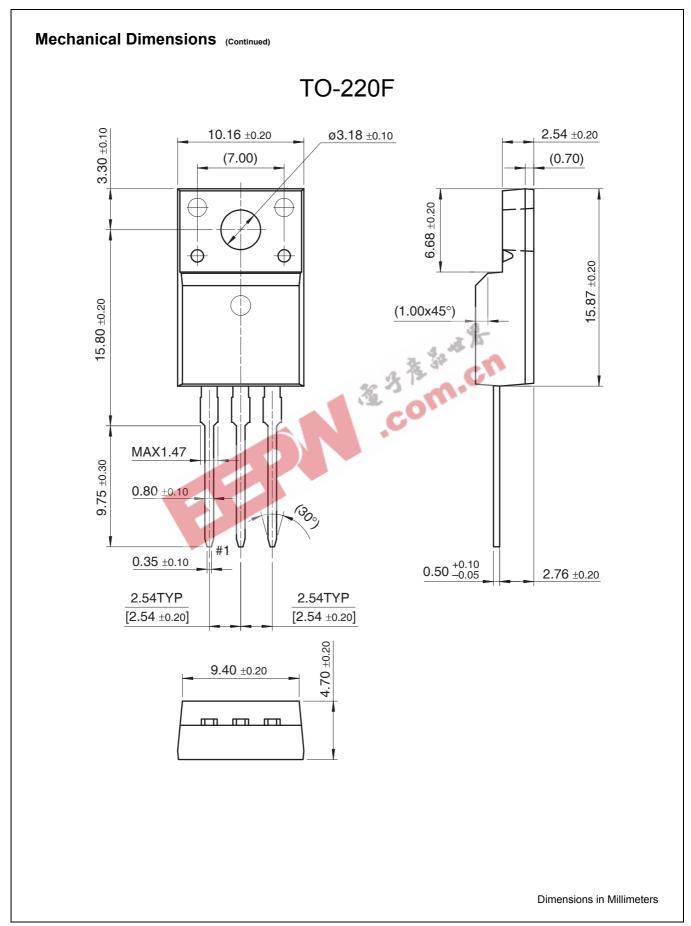


Unclamped Inductive Switching Test Circuit & Waveforms



Peak Diode Recovery dv/dt Test Circuit & Waveforms DUT IsD & Driver R_G, Same Type as DUT ≑∨m $\text{local} \, \forall_{\text{GS}}$ • dv/dt controlled by Rc \cdot I $_{\mathrm{so}}$ controlled by pulse period Gate Pulse Width V_{GS} (Driver) Gate Pulse Period 10V , Body Diode Forward Current Isp di/dt (DUT) I_{RM} Body Diode Reverse Current V_{DS} (DUT) Body Diode Recovery dv/dt V_{SD} V^{DD} Body Diode Forward Voltage Drop









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